

- ☒ (17) (((encapsula\$5 mold\$4 resin) with (leadframe lead adj f
- ☒ (1) ("6215177").pn.
- ☒ (18) (((encapsula\$5 mold\$4 resin) with (leadframe lead adj
- ☒ (79) (((chip ic die intergrated adj circuit) with (leadframe lee
- ☒ (1) (((chip ic die intergrated adj circuit) with (leadframe lea
- ☒ (1827) chip adj size adj package
- ☒ (2666) quad adj flat
- ☒ (1) (((chip ic die intergrated adj circuit) with (leadframe lea
- ☒ (4340) (chip adj size adj package) (quad adj flat)
- ☒ (12) (((chip ic die intergrated adj circuit) with (leadframe le
- ☒ (91) (((chip ic die intergrated adj circuit) with (leadframe lee
- ☒ (4344) (chip ic die intergrated adj circuit) near (stack\$3 mult
- ☒ (6) (((chip ic die intergrated adj circuit) with (leadframe lea
- ☒ (30) (((encapsula\$5 mold\$4 resin) with (leadframe lead ad

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DBs: USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

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(((encapsula\$5 mold\$4 resin) with (leadframe lead adj frame)
) with (planar align\$3) and ((stacked adj (chip ic))) (((chip ic die intergrated adj circuit) with (leadframe
 lead adj frame)
) with expos\$3 and (((encapsula\$5 mold\$4 resin) with (leadframe lead adj frame)
) with thickness) with ("same" equal))) (("6297543" "6020629").pn.) (("6215177").pn.) (((chip ic die
 intergrated adj circuit) with (leadframe lead adj frame)
) with expos\$3 with surface) with (heat thermal)) and ((chip adj size adj package) (quad adj flat)))

June 2002

BRS f...

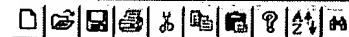
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Image

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	U	Inventor Δ	Document ID	Issue Date	Page	Title	Current OR	Current XRef	Ret
1	<input checked="" type="checkbox"/>	Asada, Junichi et al.	US 5665651 A	19970909	13	Process for encapsulating a semiconductor device and lead frame	29/827	438/123; 438/124	
2	<input checked="" type="checkbox"/>	Consis, David J. et al.	US 6215177 B1	20010410	17	Tape under frame for conventional-type IC package assembly	257/666	257/668; 257/672;	
3	<input checked="" type="checkbox"/>	Farnworth, Warren M. et al.	US 6020629 A	20000201	10	Stacked semiconductor package and method of fabrication	257/686	174/255; 257/680;	
4	<input checked="" type="checkbox"/>	Hong, Sung Hak et al.	US 6297543 B1	20011002	11	Chip scale package	257/666	257/676	
5	<input checked="" type="checkbox"/>	Horiuchi, Michio et al.	US 20020031867 A1	20020314	17	Semiconductor device and process of production of same	438/125		
6	<input checked="" type="checkbox"/>	Huang, Chien Ping	US 20020027273 A1	20020307	12	Semiconductor package and fabricating method thereof	257/678	438/106	
7	<input checked="" type="checkbox"/>	Mostafazadeh, Shahram et al.	US 6117710 A	20000912	7	Plastic package with exposed die and method of making same	438/123	438/106; 438/121	
8	<input checked="" type="checkbox"/>	Park, Sang Wook et al.	US 6137162 A	20001024	12	Chip stack package	257/685	257/686; 257/723;	
9	<input checked="" type="checkbox"/>	Asada, Junichi et al.	US 5493151 A	19960220	13	Semiconductor device, lead frame and method for manufacturing	257/686	257/666	



Drafts

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- (33) (((("5937512" "6001671").pn) and ceramic) 08/585,428 ((
- (17933) (encapsula\$5 mold\$4 resin) with (leadframe lead adj
- (0) 09/944246
- (319) ((encapsula\$5 mold\$4 resin) with (leadframe lead adj f
- (681) (stacked adj (chip ic))
- (22841) (chip ic die intergrated adj circuit) with (leadframe le
- (982) ((chip ic die intergrated adj circuit) with (leadframe lea
- (4) (((encapsula\$5 mold\$4 resin) with (leadframe lead adj fra
- (752) ((encapsula\$5 mold\$4 resin) with (leadframe lead adj f
- (464) (((chip ic die intergrated adj circuit) with (leadframe le

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DBs: USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

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) with expos\$3) and (((encapsula\$5 mold\$4 resin) with (leadframe lead adj frame)
) with thickness) with ("same" equal))) ("6297543" "6020629".pn)) ("6215177".pn)) (((chip ic die
 intergrated adj circuit) with (leadframe lead adj frame)
) with expos\$3) with surface) with (heat thermal)) and ((chip adj size adj package) (quad adj flat)))

BRS f...

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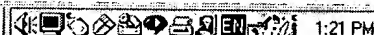
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